

Announcement

Special Issue - Electrical Discharges in Vacuum – 2024

IEEE Transactions on Plasma Science (August 2024)

Dear Colleagues,

This is the first call for the submission of papers to the “Special Issue - Electrical Discharges in Vacuum” of IEEE Transactions on Plasma Science which should be published in August 2024.

This Issue has been planned in conjunction with the 30th ISDEIV2023 Conference, held in Okinawa, Japan in 2023. So, I strongly encourage you to submit an extended version of your ISDEIV2023 contribution to this Special Issue. But this invitation is addressed also to any other Author willing to submit a manuscript relevant to the field of the Electrical Discharge in Vacuum.

Before any review process, your manuscript must pass the antiplagiarism check required by the IEEE publication policy; thus, your manuscript must be original and never published in any other Journal or Conference Proceeding. In particular, if the contribution has been accepted for publication to the ISDEIV2023 Proceedings, it **MUST BE SUBSTANTIALLY REVISED AND LENGTHENED**; on the contrary, it will be rejected for self-plagiarism.

All contributions should be submitted electronically logging in the IEEE Manuscript Central web site: <https://mc.manuscriptcentral.com/tps-ieee>

For the preparation of your manuscript, follow the instructions reported in the top-right tab “Instructions & Forms” of the IEEE Manuscript Central webpage.

To submit your paper to the Special Issue, please select “**Special Issue on Electrical Discharges in Vacuum - 2024**” in the “Type” section.

Do not send your paper to the LOC of ISDEIV 2023: it will not be processed.

All papers will undergo a standard peer-review process typical for all IEEE Transactions and Journals. **The deadline for the submission is September 30th, 2023.**

Best regards,

Yasunori Tanaka
Guest editor for the Special Issue

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